

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	704	451/56.ccls	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2004/09/22 10:37
S2	478	451/60.ccls	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2004/09/22 10:37
S3	254722	polish\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2004/09/22 10:38
S4	2208	451/41.ccls. and polish\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2004/09/22 10:38
S5	480	451/56.ccls. and polish\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2004/09/22 10:38
S6	380	451/60.ccls. and polish\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2004/09/22 10:39
S7	419839	pad	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2004/09/22 10:39
S8	46	"3-hydroxy-4-pyrones"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2004/09/22 13:04
S9	955901	("3-hydroxy-4-pyrones") or (hydroxy adj1 butyrolactones) or borane borohydrides (dialkylamine adj boranes) formaldehyde (formic adj acid) hydrogen hydroquinones hydroxylamine (hypophosphorous adj acid) trihydroxybenzene (solvated adj electrons) (sulfurous adj acid)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2004/09/22 13:15

S10	955901	("3-hydroxy-4-pyrones") or (hydroxy adj1 butyrolactones) or borane or borohydrides or (dialkylamine adj boranes) or formaldehyde or (formic adj acid) or hydrogen or hydroquinones or hydroxylamine or (hypophosphorous adj acid) or trihydroxybenzene or (solvated adj electrons) or (sulfurous adj acid)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2004/09/22 13:17
S11	303143	("428" or "156" or "51").clas	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2004/09/22 13:18
S12	43264	("3-hydroxy-4-pyrones") or (hydroxy adj1 butyrolactones) or borane borohydrides (dialkylamine adj boranes) formaldehyde (formic adj acid) hydrogen hydroquinones hydroxylamine (hypophosphorous adj acid) trihydroxybenzene (solvated adj electrons) (sulfurous adj acid)) and ("428" or "156" or "51").clas.)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2004/09/22 13:18
S13	0	"451".clas	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2004/09/22 13:18
S14	64433	"451".clas	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2004/09/22 13:18
S15	1097	("3-hydroxy-4-pyrones") or (hydroxy adj1 butyrolactones) or borane borohydrides (dialkylamine adj boranes) formaldehyde (formic adj acid) hydrogen hydroquinones hydroxylamine (hypophosphorous adj acid) trihydroxybenzene (solvated adj electrons) (sulfurous adj acid)) and "451".clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2004/09/22 13:19
S16	2868440	reducing agent	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2004/09/22 13:23

S17	834	2004/09/22 13:23	OFF	OR	US-PGPUB; USPAT; EPO; JPO; DERWENT	2004/09/22 13:23
S18	1562	2004/09/22 13:34	OFF	OR	US-PGPUB; USPAT; EPO; JPO; DERWENT	2004/09/22 13:34
S19	396	2004/09/22 13:31	OFF	OR	US-PGPUB; USPAT; EPO; JPO; DERWENT	2004/09/22 13:31
S20	263	2004/09/22 13:31	OFF	OR	US-PGPUB; USPAT; EPO; JPO; DERWENT	2004/09/22 13:31
S21	337	2004/09/22 13:42	OFF	OR	US-PGPUB; USPAT; EPO; JPO; DERWENT	2004/09/22 13:42

S22	49	2004/09/22 13:35	OFF	OR	US-PGPUB; USPAT; EPO; JPO; DERWENT	2004/09/22 13:35
S23	288	2005/01/24 13:20	OFF	OR	US-PGPUB; USPAT; EPO; JPO; DERWENT	2005/01/24 13:20
S24	93	2004/09/22 13:38	OFF	OR	US-PGPUB; USPAT; EPO; JPO; DERWENT	2004/09/22 13:38

S25	288	(("3-hydroxy-4-pyrones") or (hydroxy adj) butyrolactones) or borane borohydrides (dialkylamine adj boranes) formaldehyde (formic acid) hydrogen hydroquinones hydroxylamine (hypophosphorous adj acid) trihydroxybenzene (solvated adj electrons) (sulfurous adj acid)) and ((451/41.ccls. and polist43) and pad)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2004/09/22 13:39
S26	3038	oxidize\$4 and abrasive and polist44	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2004/09/22 14:22
S27	1	oxidize\$2 and abrasive and polist44 and (reducing adj agent) and ((liquid or aqueous) adj carrier)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2004/09/22 14:18
S28	12	("4769046" "5489233" "5527423" "5958794" "6001269" "6015506" "6062968" "6117000" "6117783" "6126532" "6290736" "6299795" "2002/0004360" "2002/0010232" "2002/0017630".PN.	USPAT	OR	OFF	2004/09/22 14:19
S29	77604	tantalum	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2004/09/22 14:22
S30	2905	451/41.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2004/09/22 14:23
S31	190	tantalum and 451/41.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2004/09/22 14:23
S32	895	(\$1-alumina or alpha-alumina or (alpha near alumina)) with abrasive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/01/21 15:29
S33	0	"451.cdas"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/01/21 15:11
S34	64929	"451".ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/01/21 15:12

S35	66	S32 and S34	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/01/21 16:01
S36	6947	(silica or (turned adj alumina)) with abrasive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/01/21 15:30
S37	1138	(S32 or S36) and S34	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/01/21 15:30
S38	11	S35 and (reducing adj agent)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/01/21 15:31
S39	27	S37 and (reducing adj agent)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/01/21 16:01
S40	1109	S36 and S34	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/01/21 16:01
S41	24	S40 and (reducing adj agent)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/01/21 16:01
S42	2	"6454822".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/01/24 09:38
S43	64929	"451".cdas	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/01/24 10:45
S44	195	S43 and ((iridium adj oxide) or (tantalum same (oxidized, oxide, oxidizer))) and ((polishing adj pad or abrasive))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/01/24 10:46
S45	195	S43 and ((iridium adj oxide) or (tantalum same (oxidized, oxide, oxidizer))) and ((polishing adj pad) or abrasive)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/01/24 09:58

S46	6	(US-20020182982-\$ or US-20030013387-\$ or US-20040029495-\$ or US-20040132385-\$).did. or (US-6454822-\$ or US-6709316-\$).did.	US-PGPUB; USPAT	OR	OFF	2005/01/24 09:59
S47	2	S45 and S46	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/01/24 10:08
S48	37	(silicone adj oxide) with "SJ"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/01/24 11:17
S49	6851	silicone near4 metal	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/01/24 10:15
S50	2852	silicone near2 metal	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/01/24 10:15
S51	740	silicone near1 metal	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/01/24 10:15
S52	1	S43 and S51	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/01/24 10:15
S53	5	S43 and S50	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/01/24 10:16
S54	11	S43 and S49	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/01/24 10:16
S55	10	S54 not S51	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/01/24 10:17

S56	6	S54 not S53	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/01/24 10:23
S57	0	S47 and (iridium adj oxide)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/01/24 10:24
S58	2	S43 and (iridium adj oxide)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/01/24 10:47
S59	212721	"428" class	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/01/24 10:46
S60	609	(substrate or wafer or semiconductor or semi-conductor) with (iridium adj oxide)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/01/24 10:49
S61	2	S43 and (iridium adj oxide)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/01/24 10:49
S62	15	((substrate or wafer or semiconductor or semi-conductor) with (iridium adj oxide)) and ((polishing adj pad) or abrasive)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/01/24 10:50
S63	1388	(copper adj oxide) with "Cu"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/01/24 11:17
S64	8	S63 and S43	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/01/24 11:17
S65	665	(iridium adj oxide) and (polish polishing CMP ("chemical mechanical polishing"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/01/24 13:23

S66	44	S65 and (reducing adj agent)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/01/24 13:23
S67	569	(Iridium adj. oxide) and (CMP ("chemical mechanical polishing"))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/01/24 13:24
S68	569	(Iridium adj. oxide) and (CMP or ("chemical mechanical polishing"))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/01/24 13:24
S69	46	(Iridium adj. oxide) same (CMP or ("chemical mechanical polishing"))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/01/24 14:09
S70	2	"4717581" .pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/01/24 14:09
S71	2	"4679572" .pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/01/24 14:11